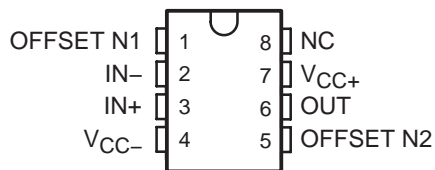


TL061, TL061A, TL061B, TL062, TL062A TL062B, TL064, TL064A, TL064B LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

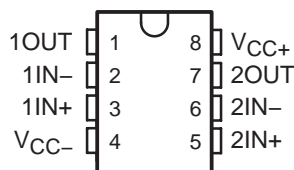
SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

- Very Low Power Consumption
- Typical Supply Current . . . 200 μ A (Per Amplifier)
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Common-Mode Input Voltage Range Includes V_{CC+}
- Output Short-Circuit Protection
- High Input Impedance . . . JFET-Input Stage
- Internal Frequency Compensation
- Latch-Up-Free Operation
- High Slew Rate . . . 3.5 V/ μ s Typ

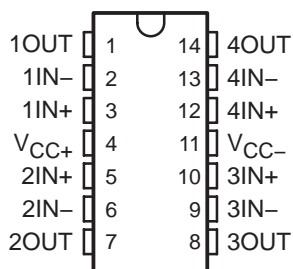
TL061, TL061A . . . D, P, OR PS PACKAGE
TL061B . . . P PACKAGE
(TOP VIEW)



TL062 . . . D, JG, P, PS, OR PW PACKAGE
TL062A . . . D, P, OR PS PACKAGE
TL062B . . . D OR P PACKAGE
(TOP VIEW)

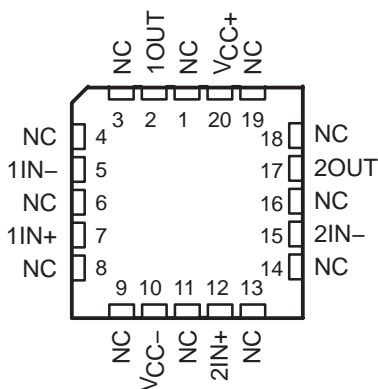


TL064 . . . D, J, N, NS, PW, OR W PACKAGE
TL064A, TL064B . . . D OR N PACKAGE
(TOP VIEW)

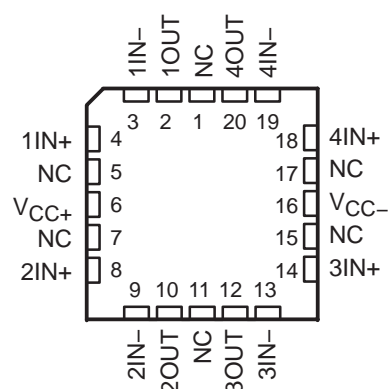


NC – No internal connection

TL062 . . . FK PACKAGE
(TOP VIEW)



TL064 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

The JFET-input operational amplifiers of the TL06_ series are designed as low-power versions of the TL08_ series amplifiers. They feature high input impedance, wide bandwidth, high slew rate, and low input offset and input bias currents. The TL06_ series features the same terminal assignments as the TL07_ and TL08_ series. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in an integrated circuit.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from –40°C to 85°C, and the M-suffix devices are characterized for operation over the full military temperature range of –55°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

**TL061, TL061A, TL061B, TL062, TL062A
 TL062B, TL064, TL064A, TL064B
 LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

description/ordering information (continued)

ORDERING INFORMATION

| TA | V _{IO} MAX AT 25°C | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING | |
|-------------|--------------------------------|------------|--------------|--------------------------|---------------------|----------|
| 0°C to 70°C | 15 mV | PDIP (P) | Tube of 50 | TL061CP | TL061CP | |
| | | | | TL062CP | TL062CP | |
| | | PDIP (N) | Tube of 25 | TL064CN | TL064CN | |
| | | SOIC (D) | Tube of 75 | TL061CD | TL061C | |
| | | | | TL061CDR | | |
| | | | Tube of 75 | TL062CD | TL062C | |
| | | | | TL062CDR | | |
| | | | Tube of 50 | TL064CD | TL064C | |
| | | | | TL064CDR | | |
| | | SOP (PS) | Reel of 2000 | TL061CPSR | T061 | |
| | | | | TL062CPSR | T062 | |
| | | SOP (NS) | Reel of 2000 | TL064CNSR | TL064 | |
| | | TSSOP (PW) | Tube of 150 | TL062CPW | T062 | |
| | | | | TL062CPWR | | |
| | | | Tube of 90 | TL064CPW | T064 | |
| | TL064CPWR | | | | | |
| | 6 mV | PDIP (P) | Tube of 50 | TL061ACP | TL061ACP | |
| | | | | TL062ACP | TL062ACP | |
| | | PDIP (N) | Tube of 25 | TL064ACN | TL064ACN | |
| | | SOIC (D) | Tube of 75 | TL061ACD | 061AC | |
| | | | | TL061ACDR | | |
| | | | Tube of 75 | TL062ACD | 062AC | |
| | | | | TL062ACDR | | |
| | | | Tube of 50 | TL064ACD | TL064AC | |
| | | | | TL064ACDR | | |
| | | SOP (PS) | Reel of 2000 | TL061ACPSR | T061A | |
| | | | | TL062ACPSR | T062A | |
| | | 3 mV | PDIP (P) | Tube of 50 | TL061BCP | TL061BCP |
| | | | | | TL062BCP | TL062BCP |
| | | | PDIP (N) | Tube of 25 | TL064BCN | TL064BCN |
| SOIC (D) | | | Tube of 75 | TL062BCD | 062BC | |
| | TL062BCDR | | | | | |
| | Tube of 50 | | TL064BCD | TL064BC | | |
| | | TL064BCDR | | | | |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

description/ordering information (continued)

ORDERING INFORMATION (continued)

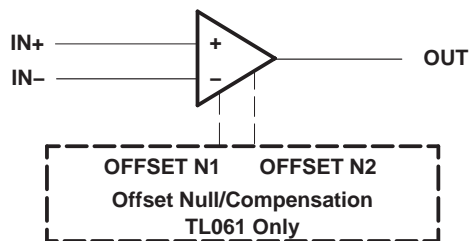
| TA | V _{IO} MAX AT 25°C | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|--------------------------------|------------|--------------|--------------------------|---------------------|
| -40°C to 85°C | 6 mV | PDIP (P) | Tube of 50 | TL061IP | TL061IP |
| | | | | TL062IP | TL062IP |
| | | PDIP (N) | Tube of 25 | TL064IN | TL064IN |
| | | SOIC (D) | Tube of 75 | TL061ID | TL061I |
| | | | | TL061IDR | |
| | | | Tube of 75 | TL062ID | TL062I |
| | | | | TL062IDR | |
| | | | Tube of 50 | TL064ID | TL064I |
| | | | | TL064IDR | |
| | | TSSOP (PW) | Reel of 2000 | TL062IPWR | TL062I |
| -55°C to 125°C | 6 mV | CDIP (JG) | Tube of 50 | TL062MJG | TL062MJG |
| | | LCCC (FK) | Tube of 55 | TL062MFK | TL062MFK |
| | 9 mV | CDIP (J) | Tube of 25 | TL064MJ | TL064MJ |
| | | CFP (W) | Tube of 150 | TL064MW | TL064MW |
| | | LCCC (FK) | Tube of 55 | TL064MFK | TL064MFK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

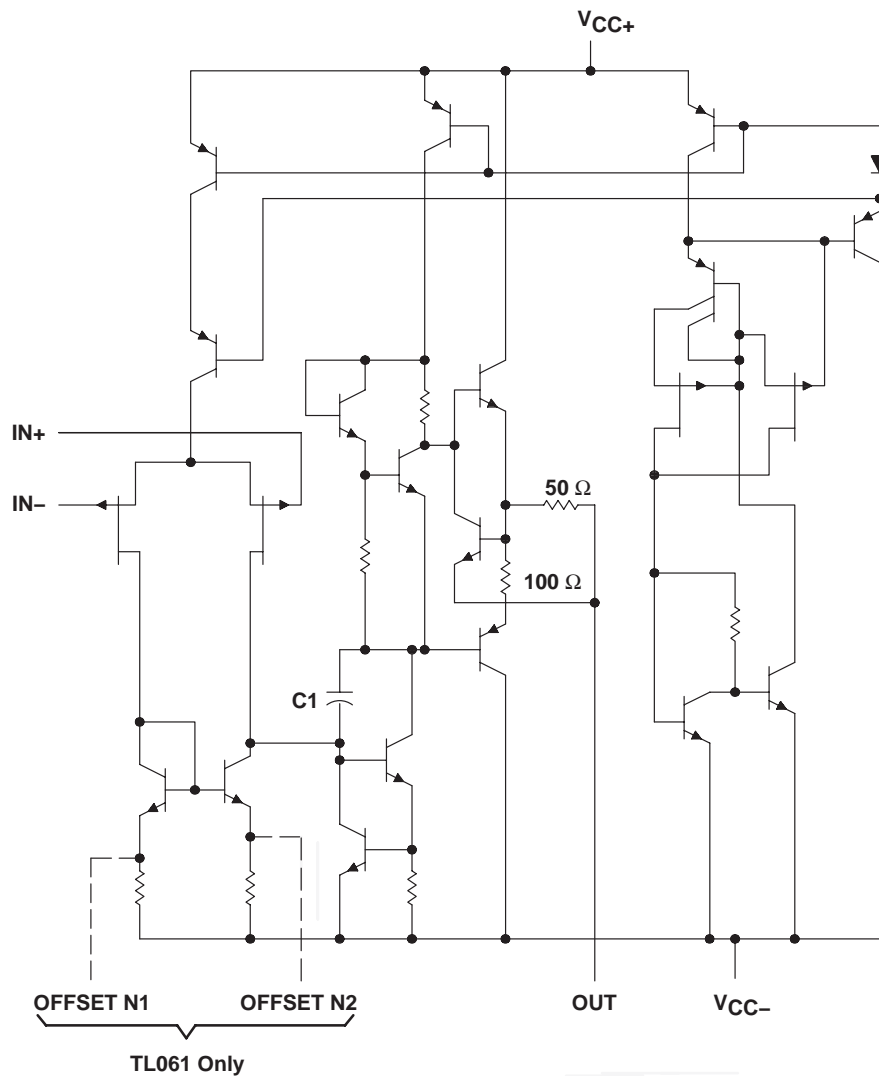
**TL061, TL061A, TL061B, TL062, TL062A
 TL062B, TL064, TL064A, TL064B
 LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

symbol (each amplifier)



schematic (each amplifier)



$C1 = 10 \text{ pF}$ on TL061, TL062, and TL064
 Component values shown are nominal.

**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | | TL06_C TL06_AC TL06_BC | TL06_I | TL06_M | UNIT |
|--|--------------------------------|------------------------------|------------|------------|------|
| Supply voltage, V_{CC+} (see Note 1) | | 18 | 18 | 18 | V |
| Supply voltage, V_{CC-} (see Note 1) | | -18 | -18 | -18 | V |
| Differential input voltage, V_{ID} (see Note 2) | | ± 30 | ± 30 | ± 30 | V |
| Input voltage, V_I (see Notes 1 and 3) | | ± 15 | ± 15 | ± 15 | V |
| Duration of output short circuit (see Note 4) | | Unlimited | Unlimited | Unlimited | |
| Package thermal impedance, θ_{JA} (see Notes 5 and 6) | D (8-pin) package | 97 | 97 | | °C/W |
| | D (14-pin) package | 86 | 86 | | |
| | N package | 80 | 80 | | |
| | NS package | 76 | 76 | | |
| | P package | 85 | 85 | | |
| | PS package | 95 | 95 | | |
| | PW (8-pin) package | 149 | 149 | | |
| Package thermal impedance, θ_{JC} (see Notes 7 and 8) | FK package | | | 5.61 | °C/W |
| | J package | | | 15.05 | |
| | JG package | | | 14.5 | |
| | W package | | | 14.65 | |
| Operating virtual junction temperature, T_J | | 150 | 150 | 150 | °C |
| Case temperature for 60 seconds | FK package | | | 260 | °C |
| Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds | J, JG, U, or W package | | | 300 | °C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | D, N, NS, P, PS, or PW package | 260 | 260 | | °C |
| Storage temperature range, T_{stg} | | -65 to 150 | -65 to 150 | -65 to 150 | °C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
- All voltage values except differential voltages are with respect to the midpoint between V_{CC+} and V_{CC-} .
 - Differential voltages are at $IN+$ with respect to $IN-$.
 - The magnitude of the input voltage should never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 - Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - The package thermal impedance is calculated in accordance with JESD 51-7.
 - Maximum power dissipation is a function of $T_J(\max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(\max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - The package thermal impedance is calculated in accordance with MIL-STD-883.



**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

electrical characteristics, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS† | TL061C TL062C TL064C | | | TL061AC TL062AC TL064AC | | | UNIT | |
|-------------------|---|--|-----|---------------------------|-------------------------------|-----------------|-----------|-----------------|------------------------------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | | |
| V_{IO} | Input offset voltage | $V_O = 0,$ $R_S = 50\ \Omega$ | | $T_A = 25^\circ\text{C}$ | 3 | 15 | 3 | 6 | mV |
| | | | | $T_A = \text{Full range}$ | 20 | | 7.5 | | |
| $\alpha_{V_{IO}}$ | Temperature coefficient of input offset voltage | $V_O = 0, R_S = 50\ \Omega,$ $T_A = \text{Full range}$ | | | 10 | | 10 | | $\mu\text{V}/^\circ\text{C}$ |
| I_{IO} | Input offset current | $V_O = 0$ | | $T_A = 25^\circ\text{C}$ | 5 | 200 | 5 | 100 | pA |
| | | | | $T_A = \text{Full range}$ | 5 | | 3 | | nA |
| I_{IB} | Input bias current‡ | $V_O = 0$ | | $T_A = 25^\circ\text{C}$ | 30 | 400 | 30 | 200 | pA |
| | | | | $T_A = \text{Full range}$ | 10 | | 7 | | nA |
| V_{ICR} | Common-mode input voltage range | $T_A = 25^\circ\text{C}$ | | | ± 11 | -12 to 15 | ± 11 | -12 to 15 | V |
| V_{OM} | Maximum peak output voltage swing | $R_L = 10\ \text{k}\Omega,$ | | $T_A = 25^\circ\text{C}$ | ± 10 | ± 13.5 | ± 10 | ± 13.5 | V |
| | | $R_L \geq 10\ \text{k}\Omega,$ | | $T_A = \text{Full range}$ | ± 10 | | ± 10 | | |
| A_{VD} | Large-signal differential voltage amplification | $V_O = \pm 10\ \text{V},$ $R_L \geq 10\ \text{k}\Omega$ | | $T_A = 25^\circ\text{C}$ | 3 | 6 | 4 | 6 | V/mV |
| | | | | $T_A = \text{Full range}$ | 3 | | 4 | | |
| B_1 | Unity-gain bandwidth | $R_L = 10\ \text{k}\Omega,$ | | $T_A = 25^\circ\text{C}$ | 1 | | 1 | | MHz |
| r_i | Input resistance | $T_A = 25^\circ\text{C}$ | | | 10^{12} | | 10^{12} | | Ω |
| CMRR | Common-mode rejection ratio | $V_{IC} = V_{ICRmin}, V_O = 0,$ $R_S = 50\ \Omega, T_A = 25^\circ\text{C}$ | | | 70 | 86 | 80 | 86 | dB |
| k_{SVR} | Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$) | $V_{CC} = \pm 9\ \text{V to } \pm 15\ \text{V},$ $V_O = 0, R_S = 50\ \Omega,$ $T_A = 25^\circ\text{C}$ | | | 70 | 95 | 80 | 95 | dB |
| P_D | Total power dissipation (each amplifier) | $V_O = 0,$ No load | | $T_A = 25^\circ\text{C},$ | 6 | 7.5 | 6 | 7.5 | mW |
| I_{CC} | Supply current (each amplifier) | $V_O = 0,$ No load | | $T_A = 25^\circ\text{C},$ | 200 | 250 | 200 | 250 | μA |
| V_{O1}/V_{O2} | Crosstalk attenuation | $A_{VD} = 100,$ | | $T_A = 25^\circ\text{C}$ | 120 | | 120 | | dB |

† All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified. Full range for T_A is 0°C to 70°C for TL06_C, TL06_AC, and TL06_BC and -40°C to 85°C for TL06_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.



**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

electrical characteristics, $V_{CC\pm} = \pm 15$ V (unless otherwise noted)

| PARAMETER | TEST CONDITION [†] | TL061BC TL062BC TL064BC | | | TL061I TL062I TL064I | | | UNIT |
|-------------------|--|---|---------------------------|-----------|----------------------------|-----------|------------------------------|---------------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | |
| V_{IO} | Input offset voltage | $V_O = 0,$ $R_S = 50 \Omega$ | $T_A = 25^\circ\text{C}$ | | 3 | | 6 | mV |
| | | | $T_A = \text{Full range}$ | | 5 | | 9 | |
| $\alpha_{V_{IO}}$ | Temperature coefficient of input offset voltage | $V_O = 0, R_S = 50 \Omega,$ $T_A = \text{Full range}$ | | 10 | | 10 | $\mu\text{V}/^\circ\text{C}$ | |
| I_{IO} | Input offset current | $V_O = 0$ | $T_A = 25^\circ\text{C}$ | | 5 | | 100 | pA |
| | | | $T_A = \text{Full range}$ | | 3 | | 10 | nA |
| I_{IB} | Input bias current [‡] | $V_O = 0$ | $T_A = 25^\circ\text{C}$ | | 30 | | 200 | pA |
| | | | $T_A = \text{Full range}$ | | 7 | | 20 | nA |
| V_{ICR} | Common-mode input voltage range | $T_A = 25^\circ\text{C}$ | | ± 11 | -12 to 15 | ± 11 | -12 to 15 | V |
| V_{OM} | Maximum peak output voltage swing | $R_L = 10 \text{ k}\Omega, T_A = 25^\circ\text{C}$ | | ± 10 | ± 13.5 | ± 10 | ± 13.5 | V |
| | | $R_L \geq 10 \text{ k}\Omega, T_A = \text{Full range}$ | | ± 10 | | ± 10 | | |
| A_{VD} | Large-signal differential voltage amplification | $V_O = \pm 10 \text{ V},$ $R_L \geq 10 \text{ k}\Omega$ | $T_A = 25^\circ\text{C}$ | | 4 | | 6 | V/mV |
| | | | $T_A = \text{Full range}$ | | 4 | | 4 | |
| B_1 | Unity-gain bandwidth | $R_L = 10 \text{ k}\Omega, T_A = 25^\circ\text{C}$ | | 1 | | 1 | | MHz |
| r_i | Input resistance | $T_A = 25^\circ\text{C}$ | | 10^{12} | | 10^{12} | | Ω |
| CMRR | Common-mode rejection ratio | $V_{IC} = V_{ICRmin}, V_O = 0,$ $R_S = 50 \Omega, T_A = 25^\circ\text{C}$ | | 80 | | 86 | | dB |
| k_{SVR} | Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$) | $V_{CC} = \pm 9 \text{ V to } \pm 15 \text{ V},$ $V_O = 0, R_S = 50 \Omega,$ $T_A = 25^\circ\text{C}$ | | 80 | | 95 | | dB |
| P_D | Total power dissipation (each amplifier) | $V_O = 0,$ No load | $T_A = 25^\circ\text{C},$ | | 6 | | 7.5 | mW |
| I_{CC} | Supply current (each amplifier) | $V_O = 0,$ No load | $T_A = 25^\circ\text{C},$ | | 200 | | 250 | μA |
| VO_1/VO_2 | Crosstalk attenuation | $A_{VD} = 100, T_A = 25^\circ\text{C}$ | | 120 | | 120 | | dB |

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T_A is 0°C to 70°C for TL06_C, TL06_AC, and TL06_BC and -40°C to 85°C for TL06_I.

[‡] Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.



**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

electrical characteristics, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS† | TL061M TL062M | | | TL064M | | | UNIT |
|---|--|---|-----------------|------------|-----------------|--------------------------|-----|------------------------------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | |
| V_{IO} Input offset voltage | $V_O = 0$, $R_S = 50\ \Omega$ | $T_A = 25^\circ\text{C}$ | | 3 | 6 | $T_A = 25^\circ\text{C}$ | | mV |
| | | $T_A = -55^\circ\text{C to } 125^\circ\text{C}$ | | 9 | | 15 | | |
| $\alpha_{V_{IO}}$ Temperature coefficient of input offset voltage | $V_O = 0$, $R_S = 50\ \Omega$, $T_A = -55^\circ\text{C to } 125^\circ\text{C}$ | 10 | | | 10 | | | $\mu\text{V}/^\circ\text{C}$ |
| I_{IO} Input offset current | $V_O = 0$ | $T_A = 25^\circ\text{C}$ | | 5 | 100 | $T_A = 25^\circ\text{C}$ | | pA |
| | | $T_A = -55^\circ\text{C}$ | | 20* | | 20* | | nA |
| | | $T_A = 125^\circ\text{C}$ | | 20 | | 20 | | |
| I_{IB} Input bias current‡ | $V_O = 0$ | $T_A = 25^\circ\text{C}$ | | 30 | 200 | $T_A = 25^\circ\text{C}$ | | pA |
| | | $T_A = -55^\circ\text{C}$ | | 50* | | 50* | | nA |
| | | $T_A = 125^\circ\text{C}$ | | 50 | | 50 | | |
| V_{ICR} Common-mode input voltage range | $T_A = 25^\circ\text{C}$ | ± 11.5 | -12 to 15 | ± 11.5 | -12 to 15 | | | V |
| V_{OM} Maximum peak output voltage swing | $R_L = 10\ \text{k}\Omega$, $T_A = 25^\circ\text{C}$ | ± 10 | ± 13.5 | ± 10 | ± 13.5 | | | V |
| | $R_L \geq 10\ \text{k}\Omega$, $T_A = -55^\circ\text{C to } 125^\circ\text{C}$ | ± 10 | | ± 10 | | | | |
| A_{VD} Large-signal differential voltage amplification | $V_O = \pm 10\ \text{V}$, $R_L \geq 10\ \text{k}\Omega$ | $T_A = 25^\circ\text{C}$ | | 4 | 6 | $T_A = 25^\circ\text{C}$ | | V/mV |
| | | $T_A = -55^\circ\text{C to } 125^\circ\text{C}$ | | 4 | | 4 | | |
| B_1 Unity-gain bandwidth | $R_L = 10\ \text{k}\Omega$, $T_A = 25^\circ\text{C}$ | | | | | | | MHz |
| r_i Input resistance | $T_A = 25^\circ\text{C}$ | 10^{12} | | | 10^{12} | | | Ω |
| CMRR Common-mode rejection ratio | $V_{IC} = V_{ICRmin}$, $V_O = 0$, $R_S = 50\ \Omega$, $T_A = 25^\circ\text{C}$ | 80 | 86 | 80 | 86 | | | dB |
| k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$) | $V_{CC} = \pm 9\ \text{V to } \pm 15\ \text{V}$, $V_O = 0$, $R_S = 50\ \Omega$, $T_A = 25^\circ\text{C}$ | 80 | 95 | 80 | 95 | | | dB |
| P_D Total power dissipation (each amplifier) | $V_O = 0$, No load | $T_A = 25^\circ\text{C}$ | | 6 | 7.5 | $T_A = 25^\circ\text{C}$ | | mW |
| I_{CC} Supply current (each amplifier) | $V_O = 0$, No load | $T_A = 25^\circ\text{C}$ | | 200 | 250 | $T_A = 25^\circ\text{C}$ | | μA |
| V_{O1}/V_{O2} Crosstalk attenuation | $A_{VD} = 100$, $T_A = 25^\circ\text{C}$ | 120 | | | 120 | | | dB |

* This parameter is not production tested.

† All characteristics are measured under open-loop conditions, with zero common-mode voltage, unless otherwise specified.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

operating characteristics, $V_{CC\pm} = \pm 15\ \text{V}$, $T_A = 25^\circ\text{C}$

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|--|-----|-----|-----|------------------------|
| SR Slew rate at unity gain (see Note 5) | $V_I = 10\ \text{V}$, $R_L = 10\ \text{k}\Omega$, $C_L = 100\ \text{pF}$, See Figure 1 | 1.5 | 3.5 | | V/ μs |
| t_r Rise time | $V_I = 20\ \text{mV}$, $C_L = 100\ \text{pF}$, See Figure 1 | 0.2 | | | μs |
| Overshoot factor | | 10% | | | |
| V_n Equivalent input noise voltage | $R_S = 20\ \Omega$, $f = 1\ \text{kHz}$ | 42 | | | nV/ $\sqrt{\text{Hz}}$ |

NOTE 5: Slew rate at $-55^\circ\text{C to } 125^\circ\text{C}$ is 0.7 V/ μs min.



PARAMETER MEASUREMENT INFORMATION

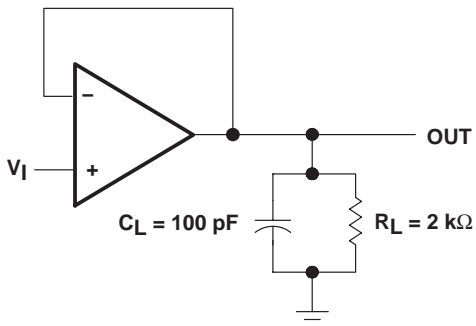


Figure 1. Unity-Gain Amplifier

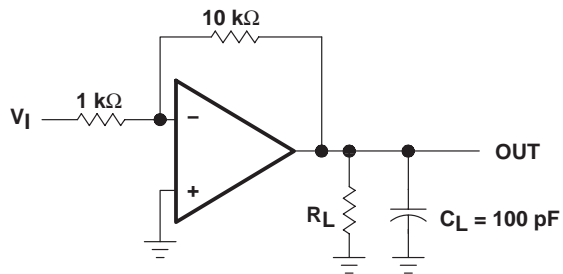


Figure 2. Gain-of-10 Inverting Amplifier

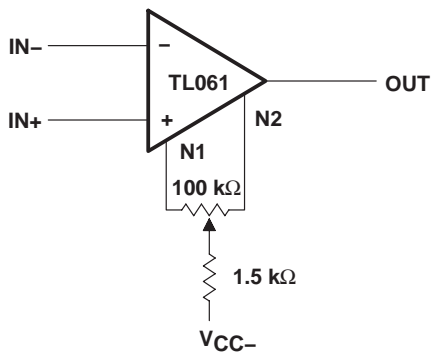


Figure 3. Input Offset-Voltage Null Circuit

TYPICAL CHARACTERISTICS

Table of Graphs

| | FIGURE |
|--|---------------|
| Maximum peak output voltage vs Supply voltage | 4 |
| Maximum peak output voltage vs Free-air temperature | 5 |
| Maximum peak output voltage vs Load resistance | 6 |
| Maximum peak output voltage vs Frequency | 7 |
| Differential voltage amplification vs Free-air temperature | 8 |
| Large-signal differential voltage amplification vs Frequency | 9 |
| Phase shift vs Frequency | 9 |
| Supply current vs Supply voltage | 10 |
| Supply current vs Free-air temperature | 11 |
| Total power dissipation vs Free-air temperature | 12 |
| Common-mode rejection ratio vs Free-air temperature | 13 |
| Normalized unity-gain bandwidth vs Free-air temperature | 14 |
| Normalized slew rate vs Free-air temperature | 14 |
| Normalized phase shift vs Free-air temperature | 14 |
| Input bias current vs Free-air temperature | 15 |
| Voltage-follower large-signal pulse response vs Time | 16 |
| Output voltage vs Elapsed time | 17 |
| Equivalent input noise voltage vs Frequency | 18 |

TL061, TL061A, TL061B, TL062, TL062A
 TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

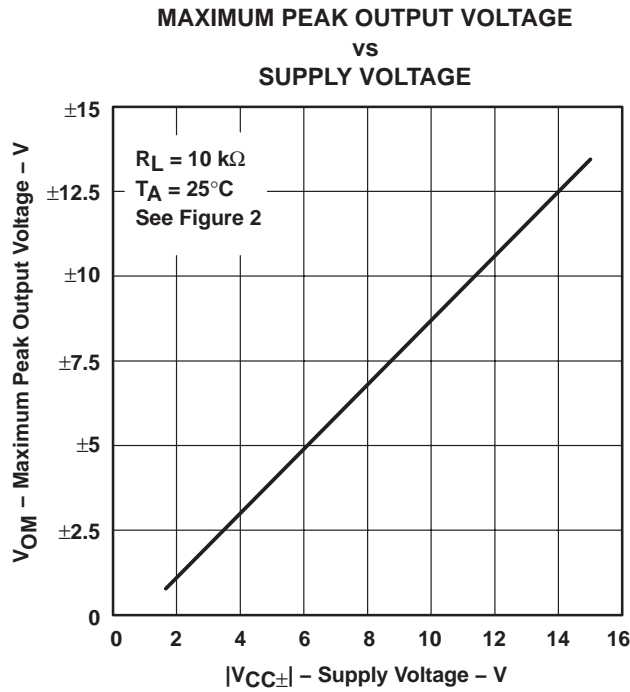


Figure 4

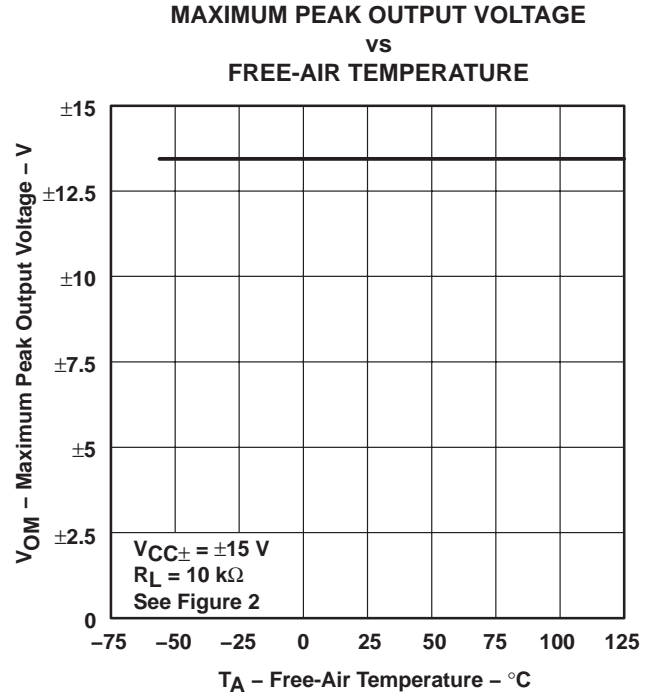


Figure 5

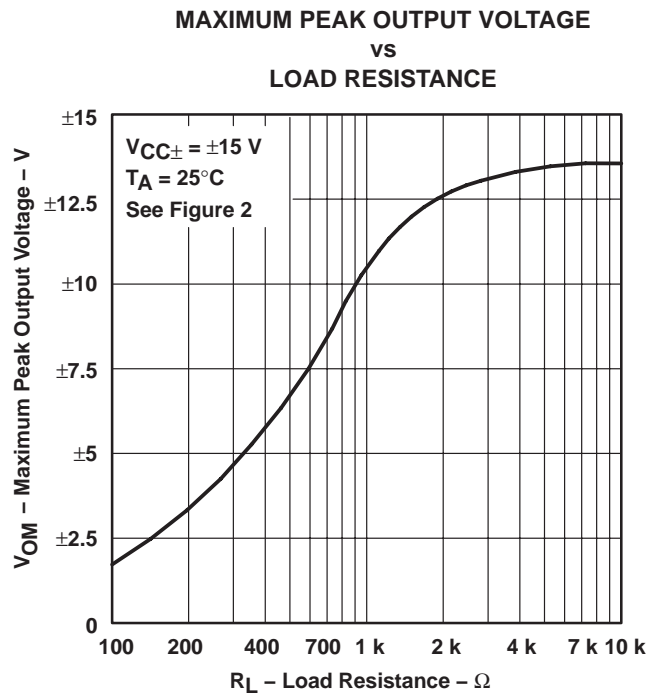


Figure 6

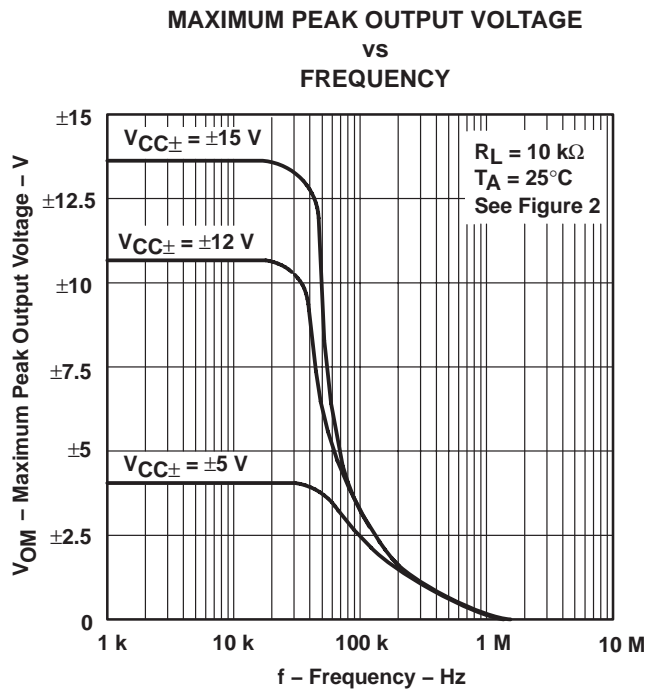


Figure 7

† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.

**TL061, TL061A, TL061B, TL062, TL062A
 TL062B, TL064, TL064A, TL064B
 LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

**DIFFERENTIAL VOLTAGE AMPLIFICATION
 vs
 FREE-AIR TEMPERATURE**

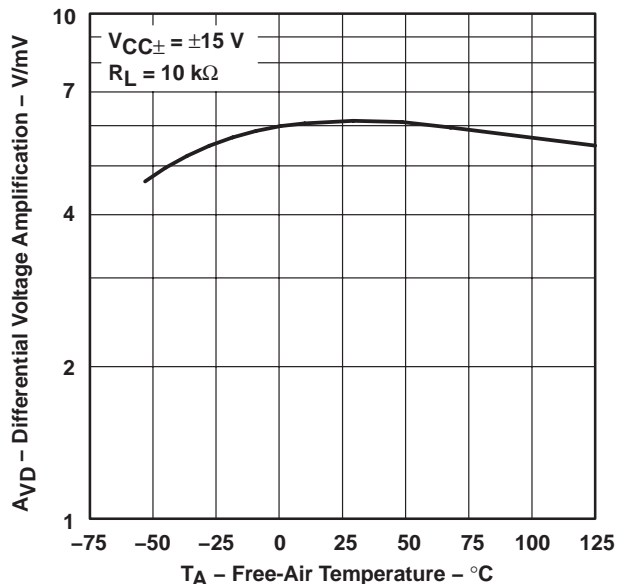


Figure 8

**LARGE-SIGNAL
 DIFFERENTIAL VOLTAGE
 AMPLIFICATION AND PHASE SHIFT
 vs
 FREQUENCY**

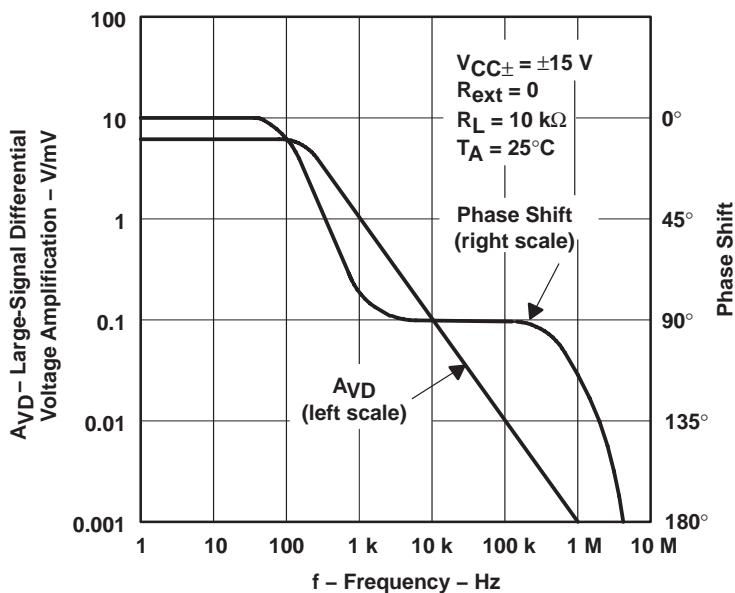


Figure 9

† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.



**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B**
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

**SUPPLY CURRENT
vs
SUPPLY VOLTAGE**

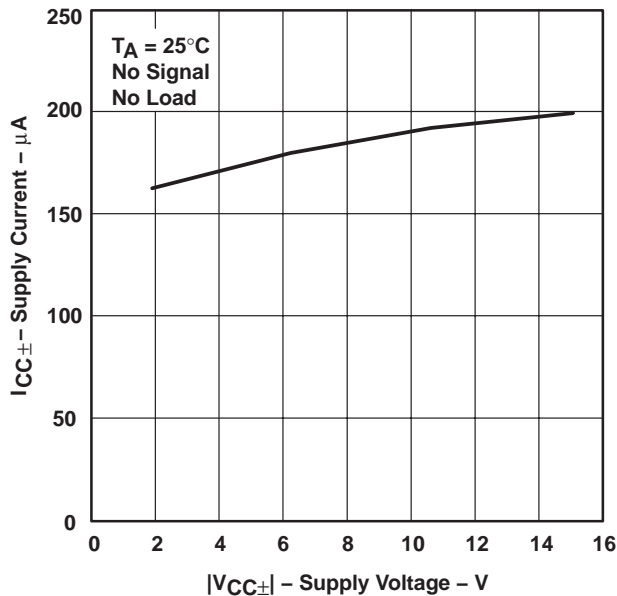


Figure 10

**SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE**

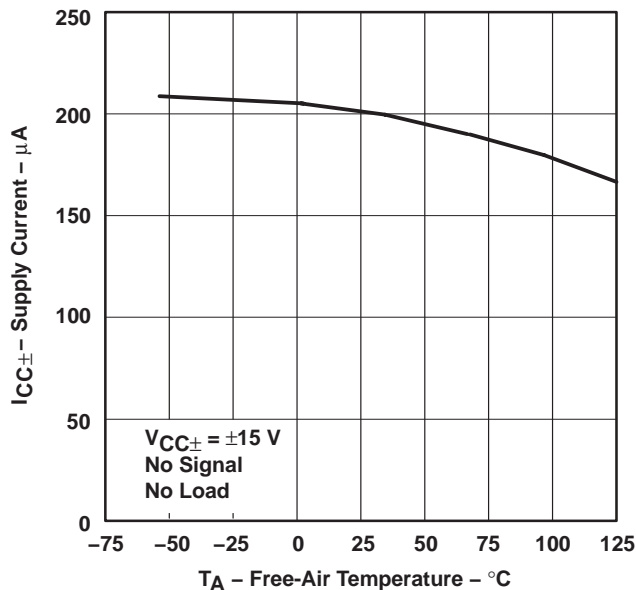


Figure 11

**TOTAL POWER DISSIPATION
vs
FREE-AIR TEMPERATURE**

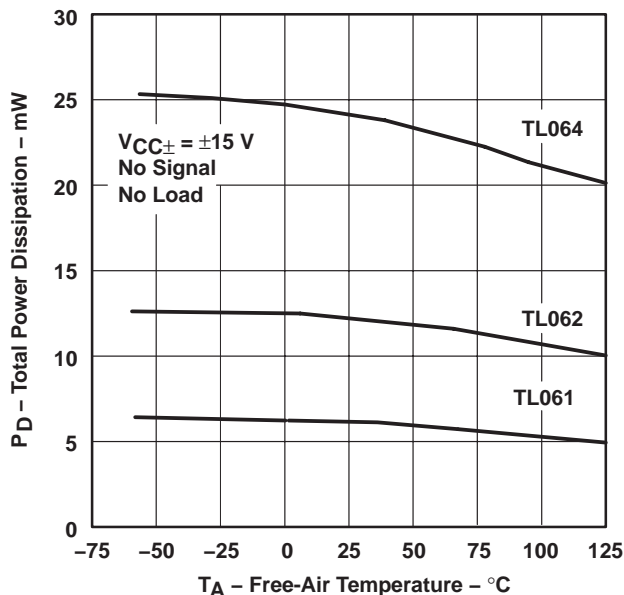


Figure 12

**ALL EXCEPT TL06_C
COMMON-MODE REJECTION RATIO
vs
FREE-AIR TEMPERATURE**

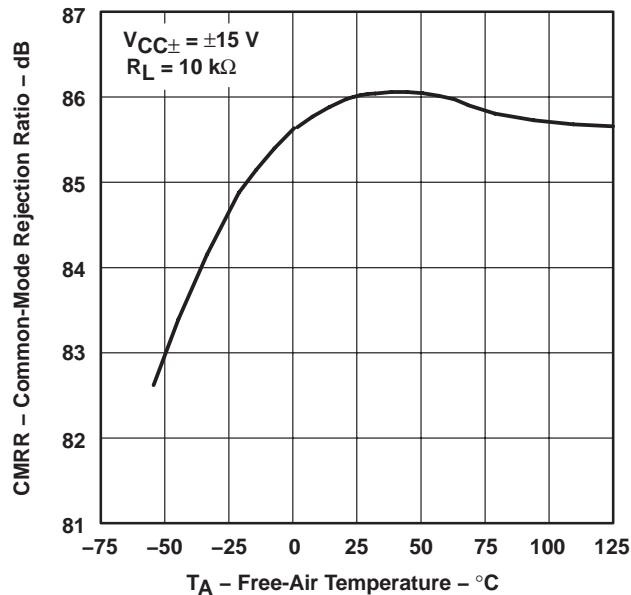


Figure 13

† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

NORMALIZED UNITY-GAIN BANDWIDTH,
 SLEW RATE, AND PHASE SHIFT
 vs
 FREE-AIR TEMPERATURE

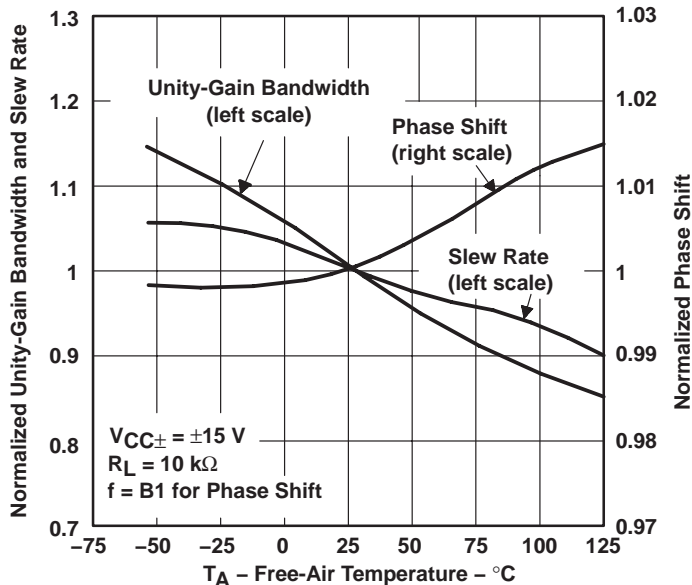


Figure 14

INPUT BIAS CURRENT
 vs
 FREE-AIR TEMPERATURE

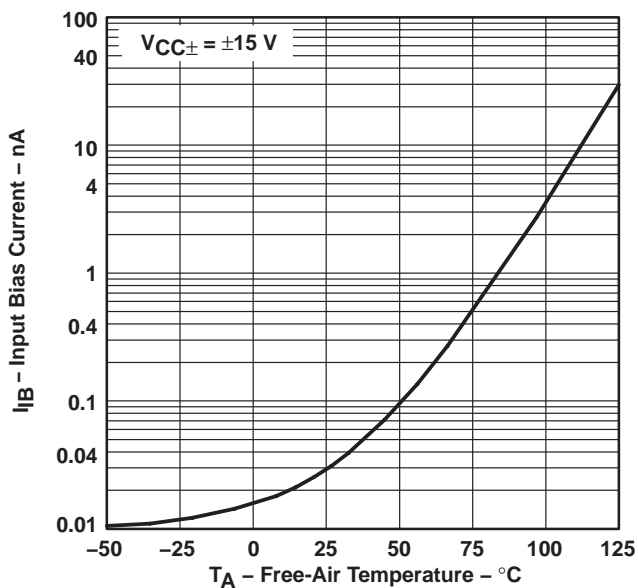


Figure 15

VOLTAGE-FOLLOWER
 LARGE-SIGNAL PULSE RESPONSE
 vs
 TIME

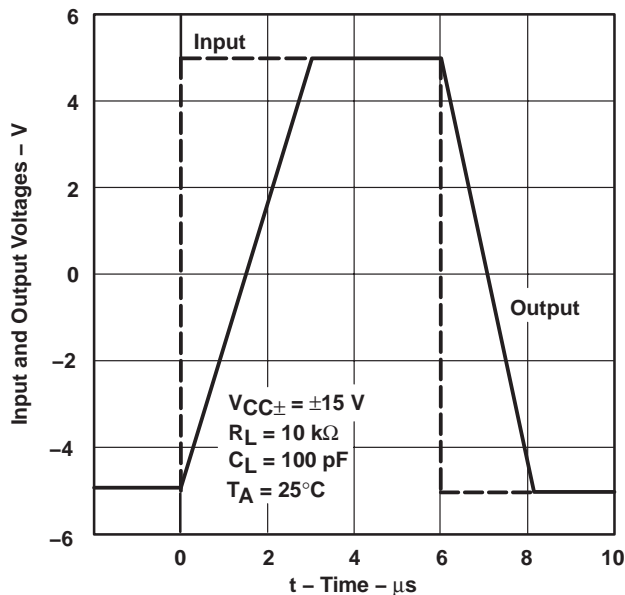
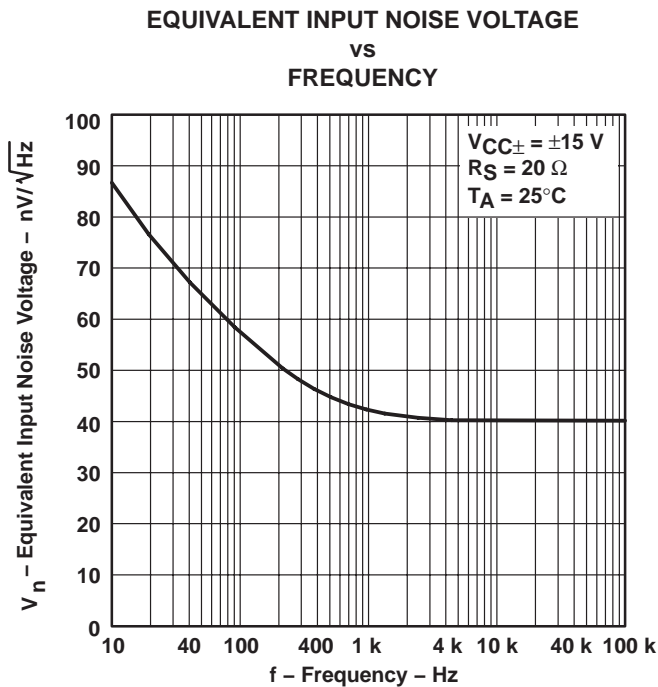
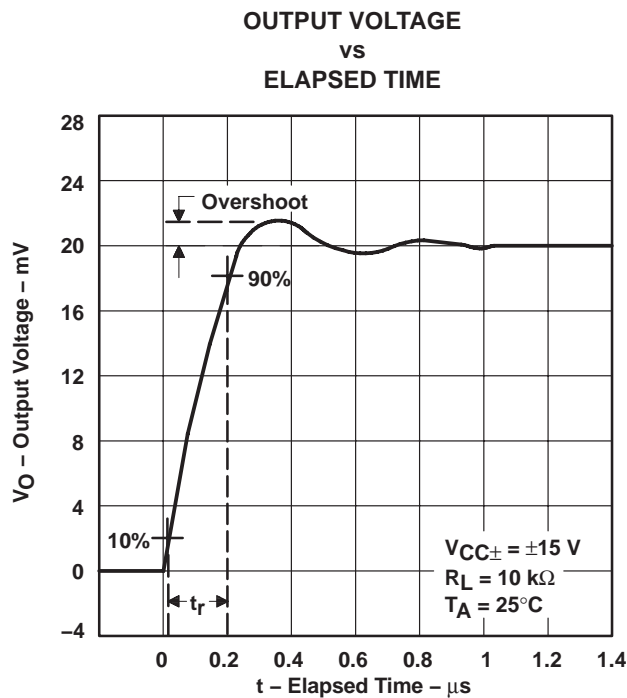


Figure 16

TL061, TL061A, TL061B, TL062, TL062A
 TL062B, TL064, TL064A, TL064B
 LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS



**TL061, TL061A, TL061B, TL062, TL062A
TL062B, TL064, TL064A, TL064B
LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS078J – NOVEMBER 1978 – REVISED SEPTEMBER 2004

APPLICATION INFORMATION

Table of Application Diagrams

| APPLICATION DIAGRAM | PART NUMBER | FIGURE |
|---|-------------|--------|
| Instrumentation amplifier | TL064 | 19 |
| 0.5-Hz square-wave oscillator | TL061 | 20 |
| High-Q notch filter | TL061 | 21 |
| Audio-distribution amplifier | TL064 | 22 |
| Low-level light detector preamplifier | TL061 | 23 |
| AC amplifier | TL061 | 24 |
| Microphone preamplifier with tone control | TL061 | 25 |
| Instrumentation amplifier | TL062 | 26 |
| IC preamplifier | TL062 | 27 |

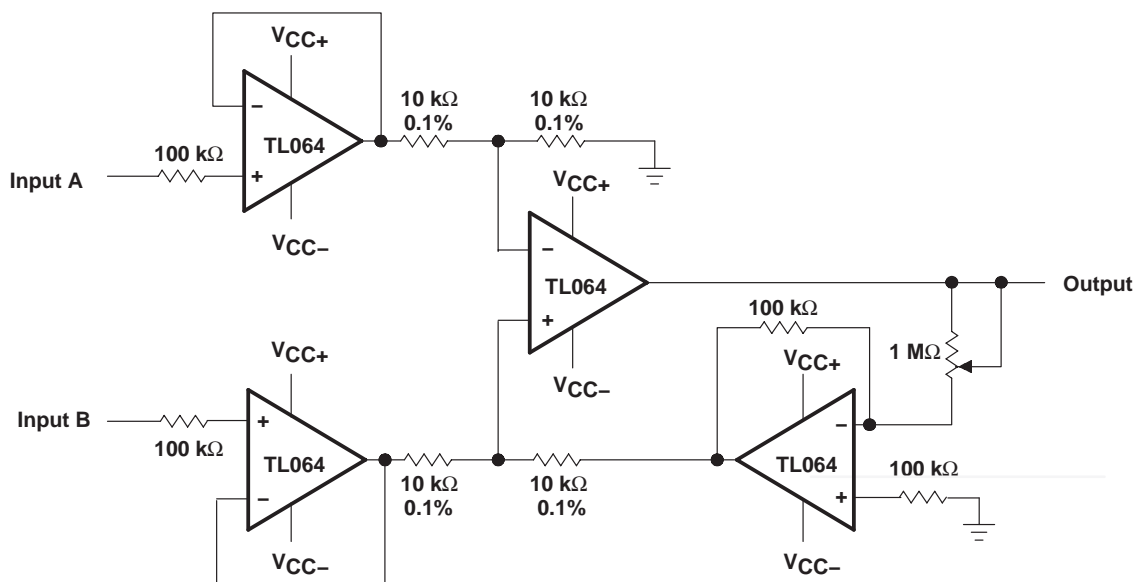


Figure 19. Instrumentation Amplifier

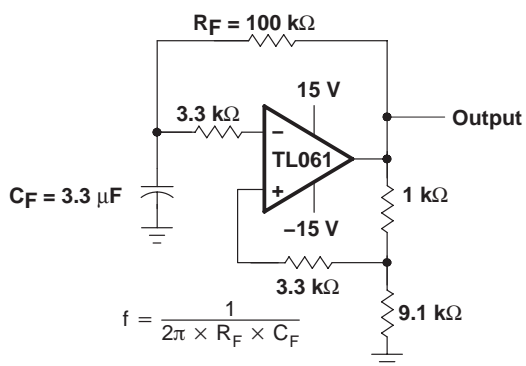


Figure 20. 0.5-Hz Square-Wave Oscillator

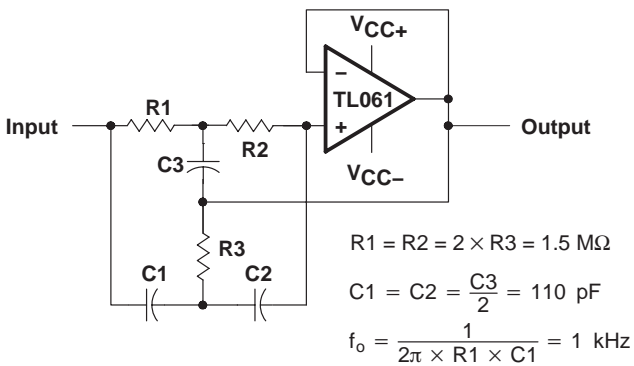


Figure 21. High-Q Notch Filter

APPLICATION INFORMATION

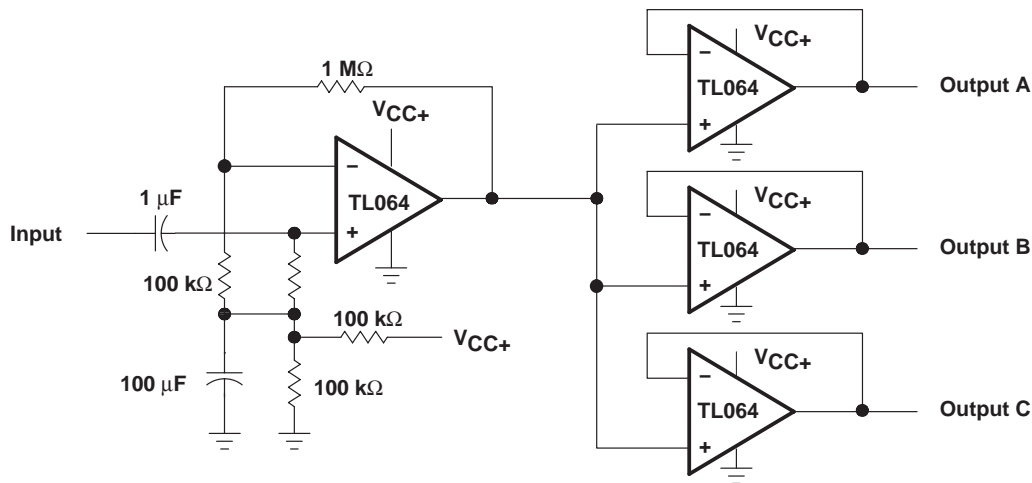


Figure 22. Audio-Distribution Amplifier

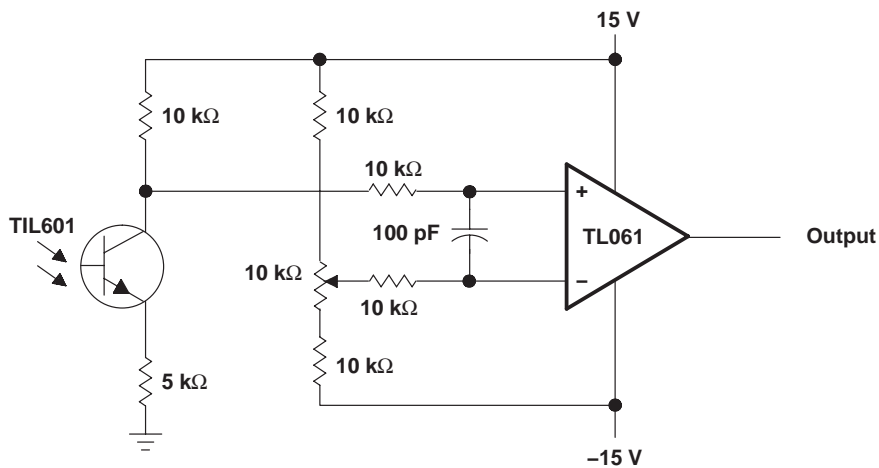


Figure 23. Low-Level Light Detector Preamplifier

APPLICATION INFORMATION

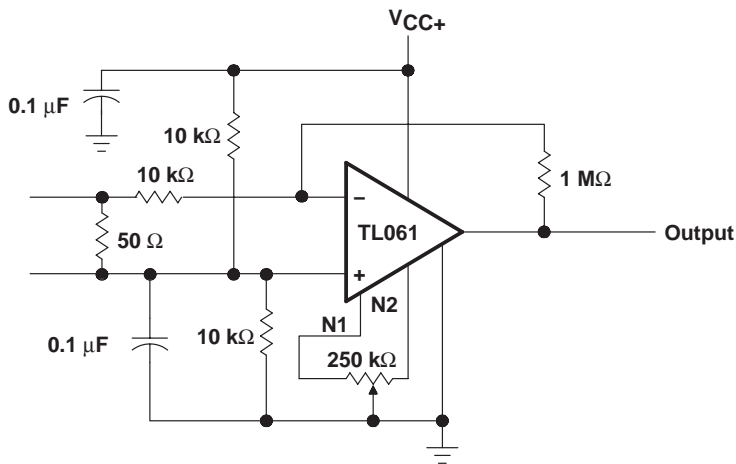


Figure 24. AC Amplifier

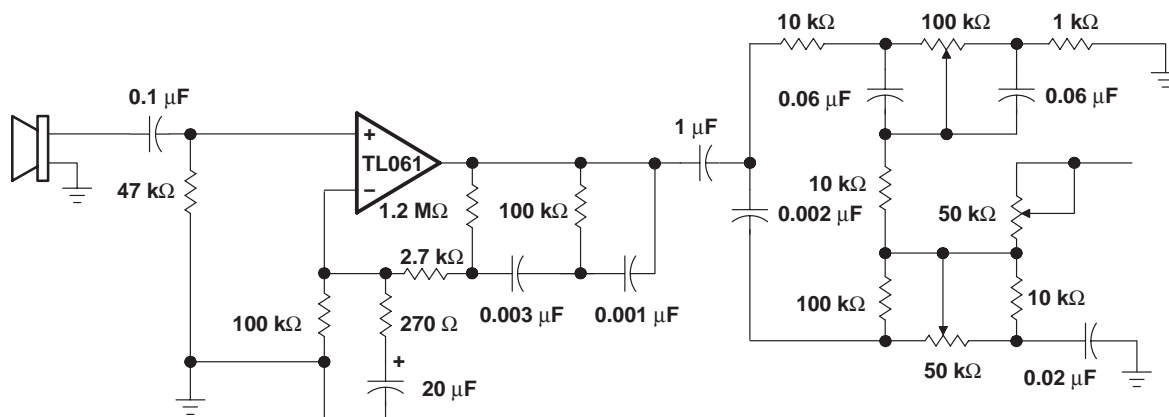


Figure 25. Microphone Preamp with Tone Control

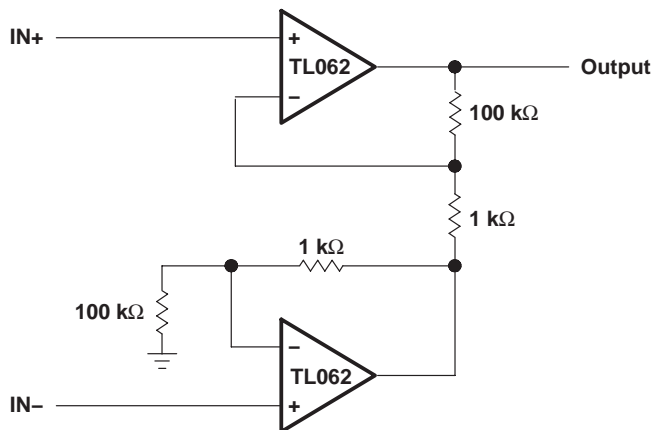


Figure 26. Instrumentation Amplifier

APPLICATION INFORMATION

IC PREAMPLIFIER RESPONSE CHARACTERISTICS

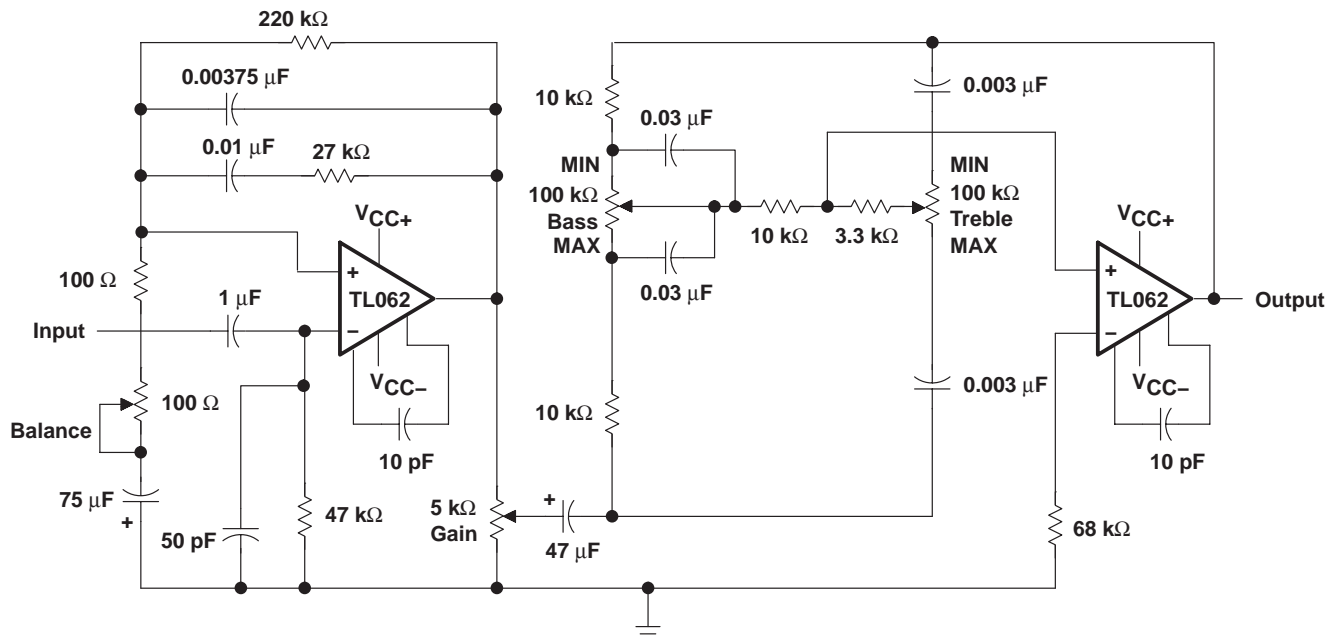
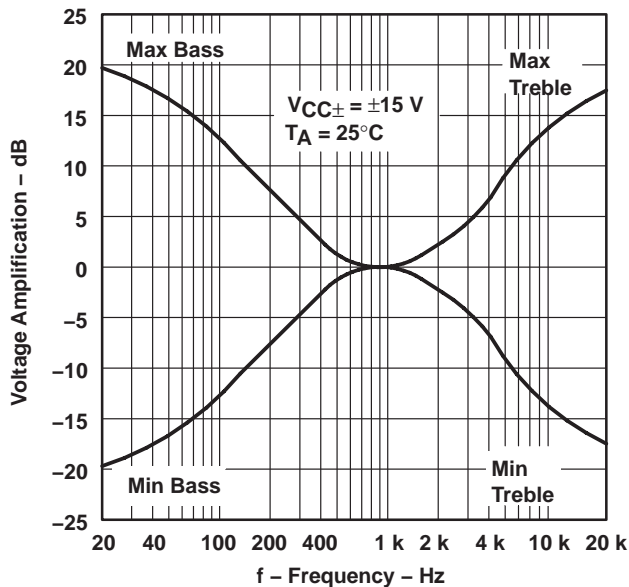


Figure 27. IC Preamplifier

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|----------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| 81023012A | OBSOLETE | LCCC | FK | 20 | | TBD | Call TI | Call TI | -55 to 125 | | |
| 81023022A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 81023022A TL062MFKB | Samples |
| 8102302HA | ACTIVE | CFP | U | 10 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102302HA TL062M | Samples |
| 8102302PA | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102302PA TL062M | Samples |
| 81023032A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 81023032A TL064MFKB | Samples |
| 8102303CA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102303CA TL064MJB | Samples |
| 8102303DA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102303DA TL064MWB | Samples |
| TL061ACD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 061AC | Samples |
| TL061ACDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 061AC | Samples |
| TL061ACDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 061AC | Samples |
| TL061ACDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 061AC | Samples |
| TL061ACDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 061AC | Samples |
| TL061ACDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 061AC | Samples |
| TL061ACP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL061ACP | Samples |
| TL061ACPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL061ACP | Samples |
| TL061BCD | OBSOLETE | SOIC | D | 8 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL061BCP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL061BCP | Samples |
| TL061BCPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL061BCP | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL061CD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL061C | Samples |
| TL061CDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL061C | Samples |
| TL061CDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL061C | Samples |
| TL061CDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL061C | Samples |
| TL061CDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL061C | Samples |
| TL061CDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL061C | Samples |
| TL061CP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL061CP | Samples |
| TL061CPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL061CP | Samples |
| TL061CPSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T061 | Samples |
| TL061CPSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T061 | Samples |
| TL061CPSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T061 | Samples |
| TL061CPWLE | OBSOLETE | TSSOP | PW | 8 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL061ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL061I | Samples |
| TL061IDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL061I | Samples |
| TL061IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL061I | Samples |
| TL061IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL061I | Samples |
| TL061IDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL061I | Samples |
| TL061IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL061I | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL061IP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TL061IP | Samples |
| TL061IPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TL061IP | Samples |
| TL061MJG | OBSOLETE | CDIP | JG | 8 | | TBD | Call TI | Call TI | -55 to 125 | | |
| TL061MJGB | OBSOLETE | CDIP | JG | 8 | | TBD | Call TI | Call TI | -55 to 125 | | |
| TL062ACD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062AC | Samples |
| TL062ACDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062AC | Samples |
| TL062ACDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062AC | Samples |
| TL062ACDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062AC | Samples |
| TL062ACDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062AC | Samples |
| TL062ACDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062AC | Samples |
| TL062ACJG | OBSOLETE | CDIP | JG | 8 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL062ACP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL062ACP | Samples |
| TL062ACPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL062ACP | Samples |
| TL062ACPSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062A | Samples |
| TL062ACPSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062A | Samples |
| TL062ACPSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062A | Samples |
| TL062BCD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062BC | Samples |
| TL062BCDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062BC | Samples |
| TL062BCDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062BC | Samples |


| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL062BCDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062BC | Samples |
| TL062BCDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062BC | Samples |
| TL062BCDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 062BC | Samples |
| TL062BCP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL062BCP | Samples |
| TL062BCPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL062BCP | Samples |
| TL062CD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL062C | Samples |
| TL062CDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL062C | Samples |
| TL062CDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL062C | Samples |
| TL062CDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL062C | Samples |
| TL062CDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL062C | Samples |
| TL062CDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL062C | Samples |
| TL062CJG | OBSOLETE | CDIP | JG | 8 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL062CP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL062CP | Samples |
| TL062CPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL062CP | Samples |
| TL062CPSLE | OBSOLETE | SO | PS | 8 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL062CPSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPW | ACTIVE | TSSOP | PW | 8 | 150 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL062CPWE4 | ACTIVE | TSSOP | PW | 8 | 150 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPWG4 | ACTIVE | TSSOP | PW | 8 | 150 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPWLE | OBSOLETE | TSSOP | PW | 8 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL062CPWR | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPWRE4 | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062CPWRG4 | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T062 | Samples |
| TL062ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL062I | Samples |
| TL062IDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL062I | Samples |
| TL062IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL062I | Samples |
| TL062IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL062I | Samples |
| TL062IDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL062I | Samples |
| TL062IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL062I | Samples |
| TL062IJG | OBSOLETE | CDIP | JG | 8 | | TBD | Call TI | Call TI | -40 to 85 | | |
| TL062IP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TL062IP | Samples |
| TL062IPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TL062IP | Samples |
| TL062IPWR | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | Z062 | Samples |
| TL062IPWRE4 | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | Z062 | Samples |
| TL062IPWRG4 | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | Z062 | Samples |
| TL062MFKB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 81023022A TL062MFKB | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL062MJG | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | TL062MJG | Samples |
| TL062MJGB | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102302PA TL062M | Samples |
| TL064ACD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064AC | Samples |
| TL064ACDE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064AC | Samples |
| TL064ACDG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064AC | Samples |
| TL064ACDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064AC | Samples |
| TL064ACDRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064AC | Samples |
| TL064ACDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064AC | Samples |
| TL064ACN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL064ACN | Samples |
| TL064ACNE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL064ACN | Samples |
| TL064ACP | ACTIVE | PDIP | NFF | 14 | 25 | TBD | Call TI | Call TI | 0 to 70 | LF444ACN | Samples |
| TL064BCD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064BC | Samples |
| TL064BCDE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064BC | Samples |
| TL064BCDG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064BC | Samples |
| TL064BCDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064BC | Samples |
| TL064BCDRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064BC | Samples |
| TL064BCDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064BC | Samples |
| TL064BCN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL064BCN | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL064BCNE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL064BCN | Samples |
| TL064BCP | ACTIVE | PDIP | NFF | 14 | 25 | TBD | Call TI | Call TI | 0 to 70 | LF444ACN | Samples |
| TL064CD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064C | Samples |
| TL064CDE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064C | Samples |
| TL064CDG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064C | Samples |
| TL064CDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064C | Samples |
| TL064CDRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064C | Samples |
| TL064CDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064C | Samples |
| TL064CN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL064CN | Samples |
| TL064CNE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TL064CN | Samples |
| TL064CNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064 | Samples |
| TL064CNSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064 | Samples |
| TL064CNSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TL064 | Samples |
| TL064CP | ACTIVE | PDIP | NFF | 14 | 25 | TBD | Call TI | Call TI | 0 to 70 | LF444CN | Samples |
| TL064CPW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T064 | Samples |
| TL064CPWE4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T064 | Samples |
| TL064CPWG4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T064 | Samples |
| TL064CPWLE | OBSOLETE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| TL064CPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T064 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| TL064CPWRE4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T064 | Samples |
| TL064CPWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | T064 | Samples |
| TL064ID | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064IDE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064IDG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064IDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064IDRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064IDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064IN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TL064IN | Samples |
| TL064INE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TL064IN | Samples |
| TL064INS | ACTIVE | SO | NS | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064INSG4 | ACTIVE | SO | NS | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064INSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064INSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TL064I | Samples |
| TL064MFK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | TL064MFK | Samples |
| TL064MFKB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 81023032A TL064MFKB | Samples |
| TL064MJ | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | TL064MJ | Samples |
| TL064MJB | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102303CA TL064MJB | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|------------------|----------------------|--------------|-------------------------|---|
| TL064MWB | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8102303DA TL064MWB |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TL062, TL062M, TL064, TL064M :

- Catalog: [TL062](#), [TL064](#)

- Military: [TL062M](#), [TL064M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

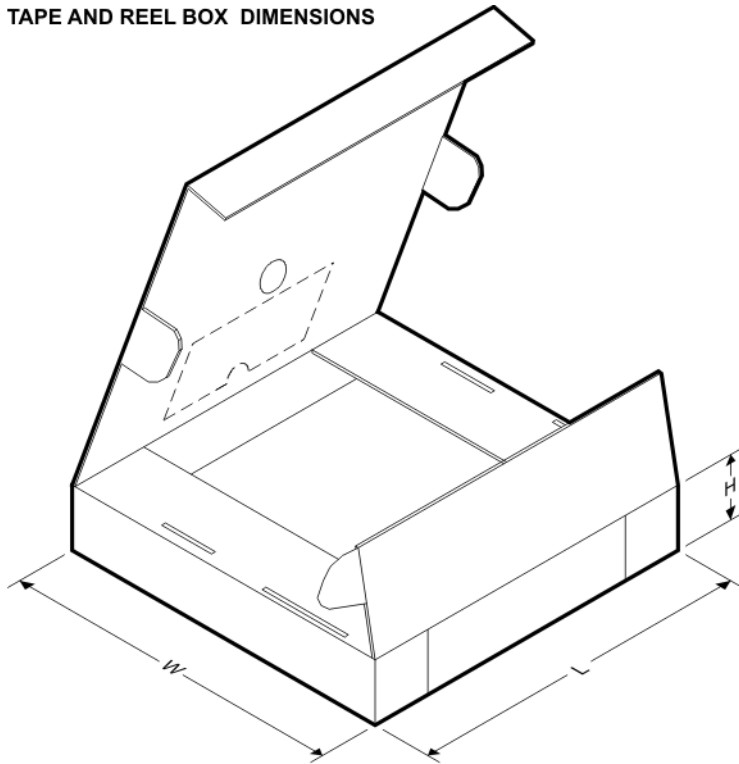
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TL061ACDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL061CDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL061CDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL061CPSR | SO | PS | 8 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| TL061IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL061IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062ACDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062ACPSR | SO | PS | 8 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| TL062BCDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062CDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062CDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062CPWR | TSSOP | PW | 8 | 2000 | 330.0 | 12.4 | 7.0 | 3.6 | 1.6 | 8.0 | 12.0 | Q1 |
| TL062IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TL062IPWR | TSSOP | PW | 8 | 2000 | 330.0 | 12.4 | 7.0 | 3.6 | 1.6 | 8.0 | 12.0 | Q1 |
| TL064ACDR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| TL064BCDR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| TL064CPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TL064IDR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| TL064IDRG4 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| TL064INSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TL061ACDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL061CDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| TL061CDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL061CPSR | SO | PS | 8 | 2000 | 367.0 | 367.0 | 38.0 |
| TL061IDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| TL061IDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL062ACDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL062ACPSR | SO | PS | 8 | 2000 | 367.0 | 367.0 | 38.0 |
| TL062BCDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL062CDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| TL062CDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL062CPWR | TSSOP | PW | 8 | 2000 | 367.0 | 367.0 | 35.0 |
| TL062IDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| TL062IDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TL062IPWR | TSSOP | PW | 8 | 2000 | 367.0 | 367.0 | 35.0 |
| TL064ACDR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| TL064BCDR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| TL064CPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| TL064IDR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| TL064IDRG4 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| TL064INSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |

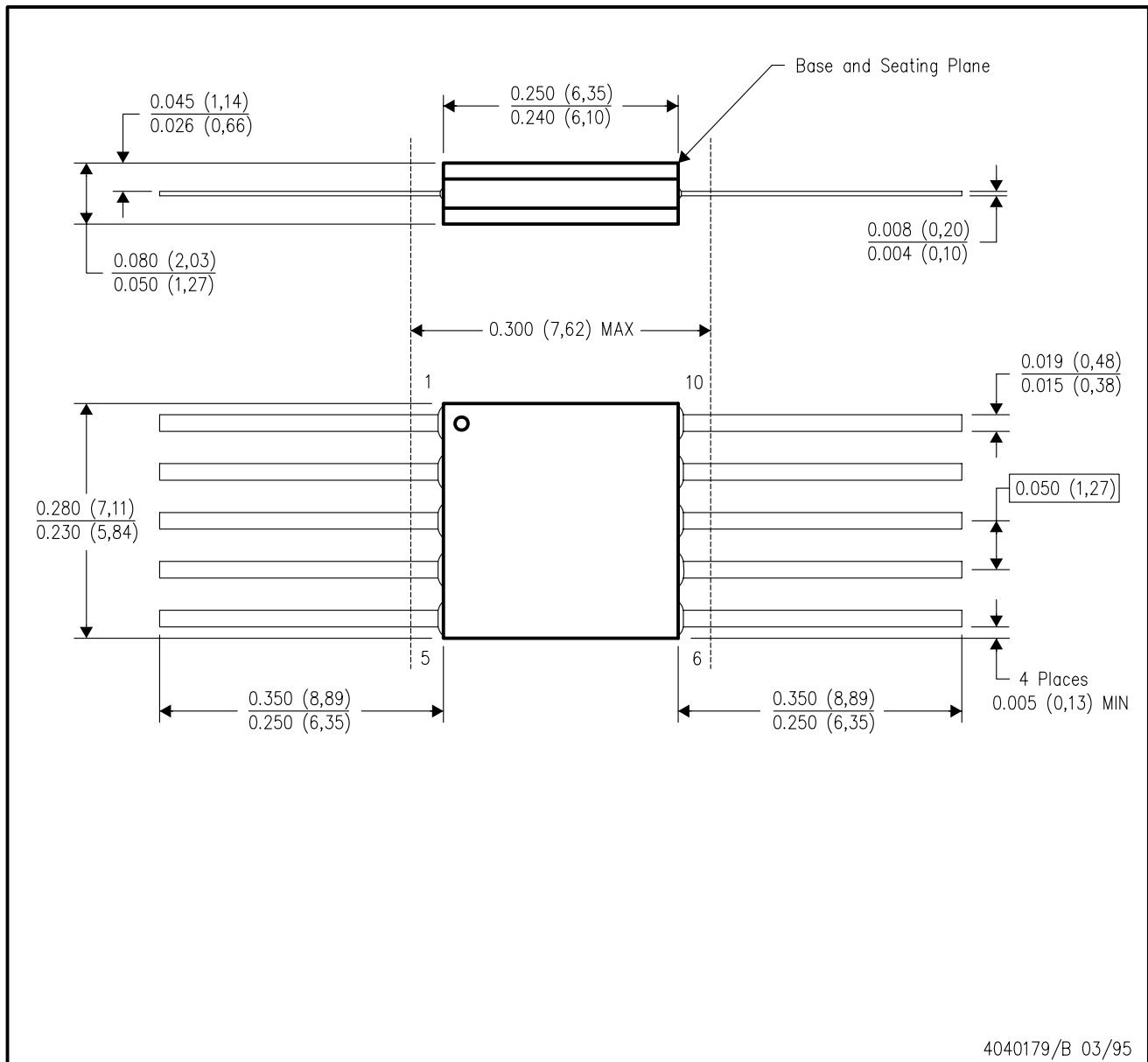


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



4040082/E 04/2010

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

N (R-PDIP-T**)

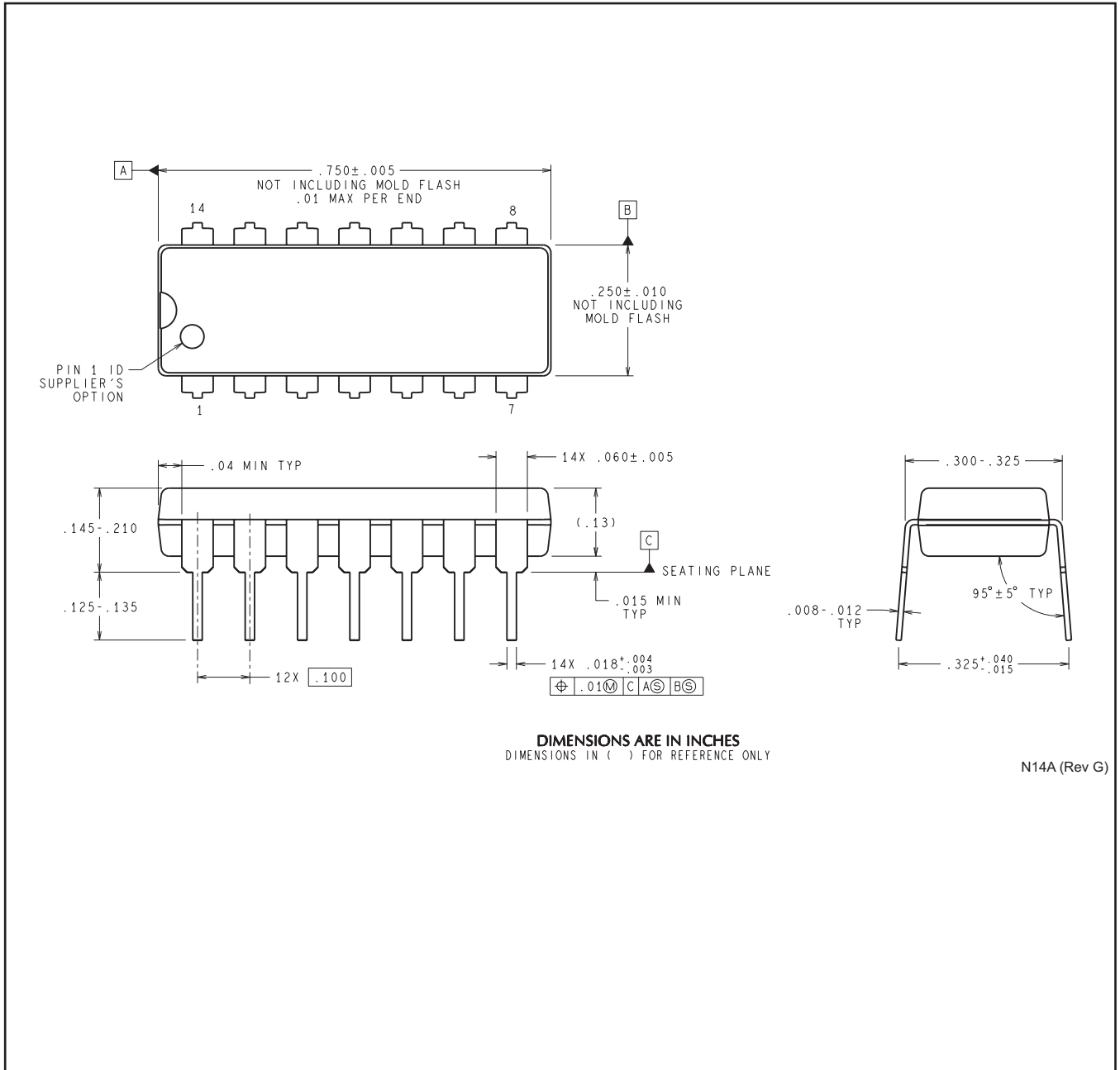
PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

NFF0014A



DIMENSIONS ARE IN INCHES
 DIMENSIONS IN () FOR REFERENCE ONLY

N14A (Rev G)

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

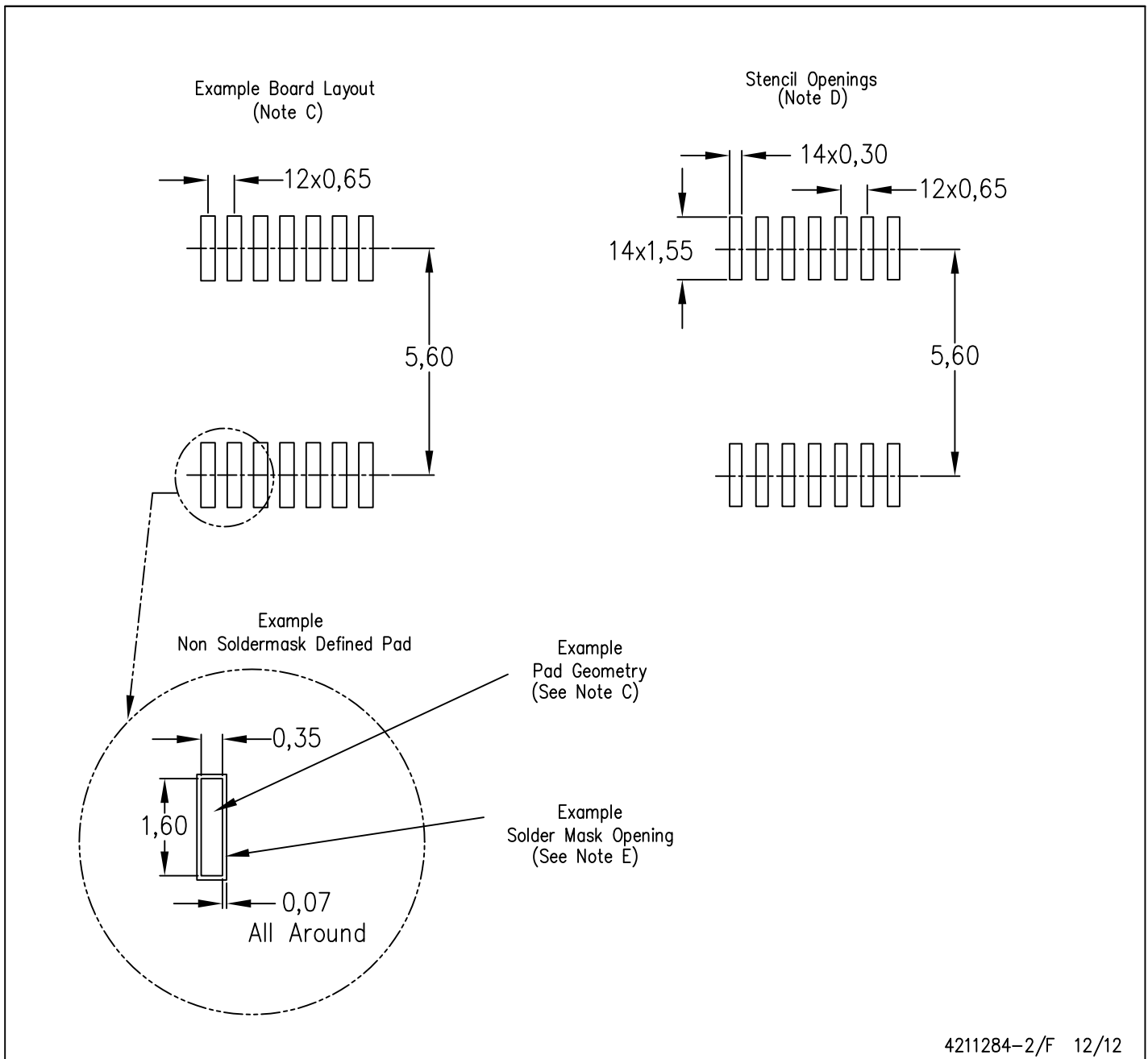
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

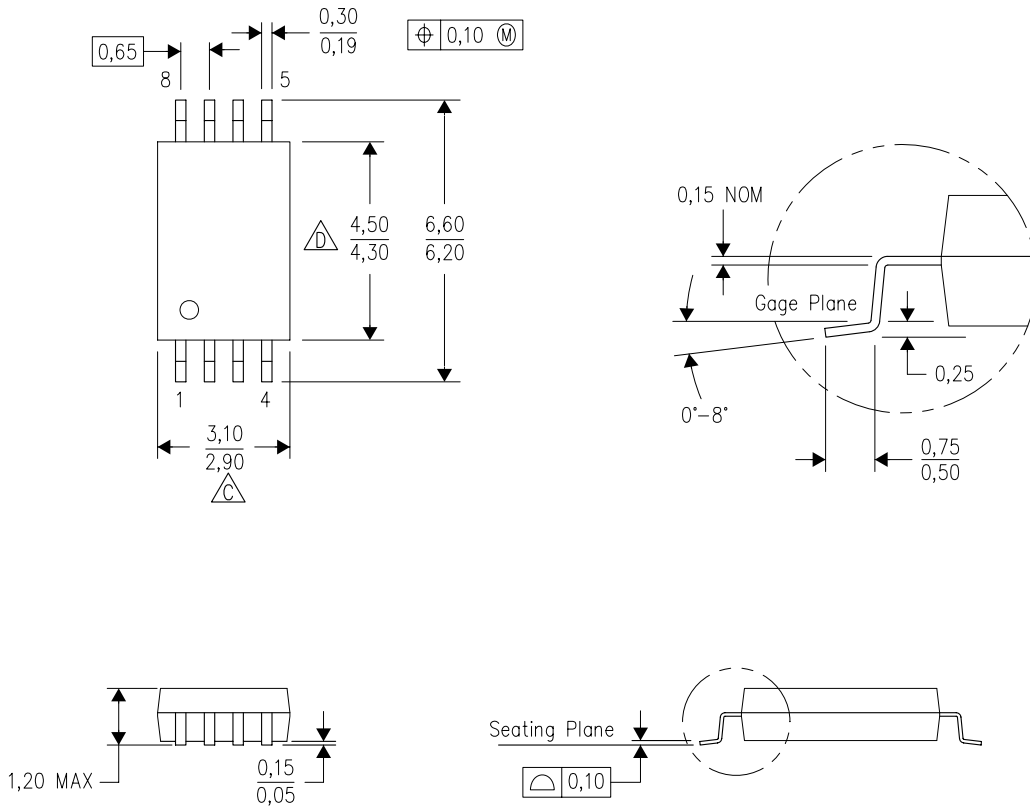
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4040064-2/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

| | |
|------------------------------|--|
| Audio | www.ti.com/audio |
| Amplifiers | amplifier.ti.com |
| Data Converters | dataconverter.ti.com |
| DLP® Products | www.dlp.com |
| DSP | dsp.ti.com |
| Clocks and Timers | www.ti.com/clocks |
| Interface | interface.ti.com |
| Logic | logic.ti.com |
| Power Mgmt | power.ti.com |
| Microcontrollers | microcontroller.ti.com |
| RFID | www.ti-rfid.com |
| OMAP Applications Processors | www.ti.com/omap |
| Wireless Connectivity | www.ti.com/wirelessconnectivity |

Applications

| | |
|-------------------------------|--|
| Automotive and Transportation | www.ti.com/automotive |
| Communications and Telecom | www.ti.com/communications |
| Computers and Peripherals | www.ti.com/computers |
| Consumer Electronics | www.ti.com/consumer-apps |
| Energy and Lighting | www.ti.com/energy |
| Industrial | www.ti.com/industrial |
| Medical | www.ti.com/medical |
| Security | www.ti.com/security |
| Space, Avionics and Defense | www.ti.com/space-avionics-defense |
| Video and Imaging | www.ti.com/video |

TI E2E Community

e2e.ti.com